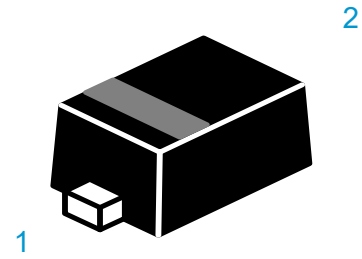


Features

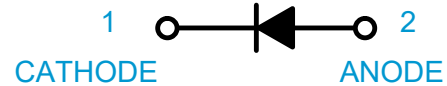
- High Speed Switching
- Low IR
- Surface Device Type Mounting
- Small SMD Package
- RoHS Compliant



SOD-523

Applications

- Inverse-polarity protection
- Portable Applications i.e. PDA, Cell Phone, etc.



Order information

Device	Marking	Shipping
1N4148WT	E1 *	8,000/Tape &Reel

Absolute Maximum Ratings

Parameter	Symbol	Limits	Unit
Repetitive Peak Reverse Voltage	VRRM	100	V
Maximum Average Forward Current	IF	150	mA
Forward Surge Current @1uS	IFSM	2	A
Storage Temperature	TSTG	-55~+125	°C
Operating Junction Temperature	TJ,TSTG	-55~+125	°C
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	TL	260	°C
Junction-to-Ambient – Steady State (Note 1)	RθJA	130	°C/W

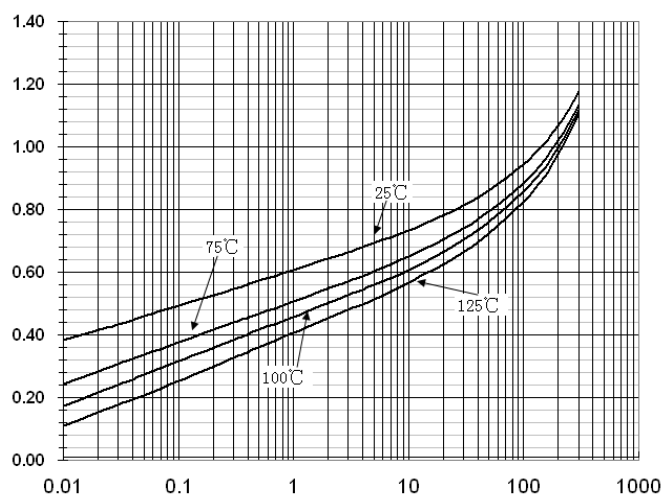
Note 1:

Surface-mounted on FR4 board using 1 inchsquarepad size (Cu area = 1.127 inch square [1 oz] including traces)

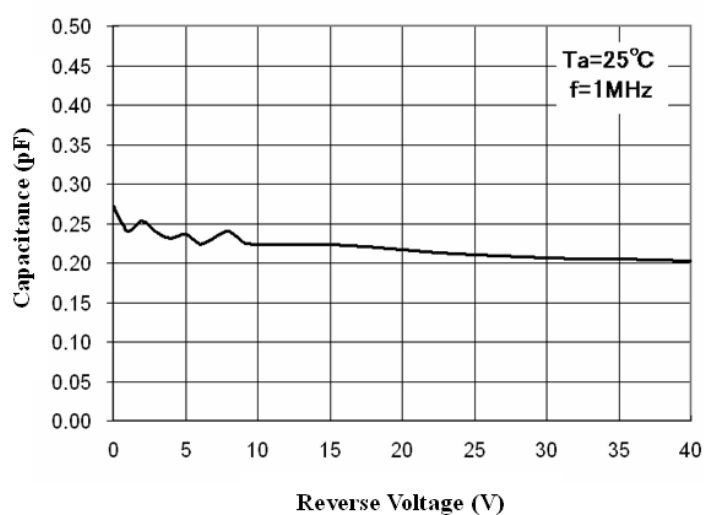
Electrical Characteristic (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Break Down Voltage (IR=100uA) (IR=5uA)	Vbr	100 75		-	V
Reverse Leakage Current (VR=20V) (VR=75V)	IR			0.025 5	μA
Forward Voltage (IF=10mA)	VF			1	V
Reverse Recovery Time (IF=10mA, IR=60mA, RL=100W, IRR=1mA)	Trr			4	nS
Capacitance (VR=0V, f=1MHZ)	Cj			4	pF

Characteristic Curves

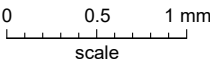
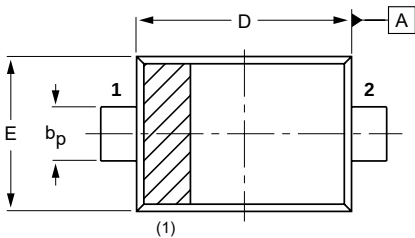
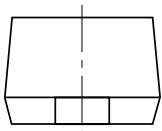
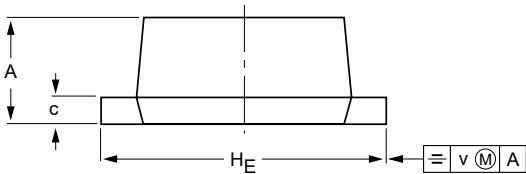


F1. Forward Voltage vs Ambient Temperature



F2. Total Capacitance

Outline and Dimensions



DIMENSIONS (mm are the original dimensions)

UNIT	A	b _p	c	D	E	H _E	v
mm	0.70 0.50	0.34 0.26	0.17 0.11	1.25 1.15	0.85 0.75	1.65 1.55	0.1